December 11, 1995

Product Change Notification PCN95009

Qualification of the Advanced Semiconductor Engineering, Inc.

Subject: Qualification of the Advanced Semiconductor Engineering, Inc. (ASE) Assembly Facility to Assemble Plastic Quad Flat Packs (TQ, PQ) for Xilinx products.

Products Affected: Plastic Quad Flat Packs (TQ, PQ).

Change Description: The ASE Assembly Facility, located in Malaysia, will start production of Plastic Quad Flat Pack products for Xilinx, after successfully completing qualification testing, in February, 1996. Currently this facility is already qualified for assembly manufacturing of Xilinx PLCC and PDip products.

Product Change: There are no changes in electrical or mechanical specifications. The package piece parts (mold compound, leadframe, etc.) as well as the manufacturing processes are totally compatible with Plastic Quad Flat Pack products that Xilinx currently supplies from other assembly facilities.

Reason For Change: To provide additional assembly capacity for Xilinx Plastic Quad Flat Pack products. This addition is being made in support of our continuous effort towards improving total customer satisfaction.

Qualification Data: Xilinx performed an on-site audit of this facility in May, 1995, and verified ASE's conformance to Xilinx' and ISO-9002 quality system requirements. Reliability Qualification Testing is in progress. Summary qualification test data will be made available upon completion of all required testing (currently estimated to be February, 1996).

Traceability: For traceability purposes, the back (bottom) side marking will show an "M" prefix on the assembly lot code.

Immediate response to this notification is not required. For any questions regarding this PCN you may contact Xilinx via email at "pcn@xilinx.com", or by FAX at (408) 559-1368.

Xilinx PCN, PDNs, and Advisories are available at: http://www.xilinx.com/partinfo/notify/notify.htm